

### GENERAL DESCRIPTION



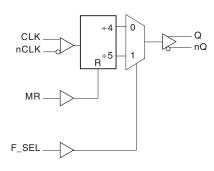
The ICS87354I is a high performance ÷4/÷5 Differential-to-3.3V LVPECL Clock Generator and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The CLK, nCLK pair can accept most standard differ-

ential input levels. The ICS87354I is characterized to operate from a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS87354I ideal for those clock distribution applications demanding well defined performance and repeatability.

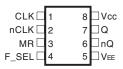
#### **F**EATURES

- One differential 3.3V LVPECL output
- · One CLK, nCLK input pair
- CLK, nCLK pair can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- · Maximum clock input frequency: 1GHz
- Translates any single ended input signal (LVCMOS, LVTTL, GTL) to LVPECL levels with resistor bias on nCLK input
- Part-to-part skew: 300ps (maximum)
- · Propagation delay: 2.1ns (maximum)
- LVPECL mode operating voltage supply range:  $V_{CC} = 3.0V$  to 3.465V,  $V_{FF} = 0V$
- -40°C to 85°C ambient operating temperature
- · Lead-Free package fully RoHS compliant

### **BLOCK DIAGRAM**



### PIN ASSIGNMENT



ICS87354I 8-Lead SOIC

3.90mm x 4.90mm x 1.37mm package body **M Package** Top View

TABLE 1. PIN DESCRIPTIONS

Number	Name	Ту	/ре	Description
1	CLK	Input	Pulldown	Non-inverting differential clock input.
2	nCLK	Input	Pullup	Inverting differential clock input.
3	MR	Input	Pulldown	Active High Master Reset. When logic HIGH, the internal dividers are reset causing the true output (Q) to go low and the inverted output (nQ) to go high. When logic LOW, the internal dividers and the output are enabled. LVCMOS / LVTTL interface levels. See Table 3.
4	F_SEL	Input	Pulldown	Selects divider value for Q, nQ outputs as described in Table 3. LVCMOS / LVTTL interface levels.
5	$V_{\rm EE}$	Power		Negative supply pin.
6, 7	Q, nQ	Output		Differential output pair. LVPECL interface levels.
8	V <sub>cc</sub>	Power		Positive supply pin.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ

TABLE 3. FUNCTION TABLE

MR	F_SEL	Divide Value
1	Х	Reset: Q output low, nQ output high
0	0	÷4
0	1	÷5

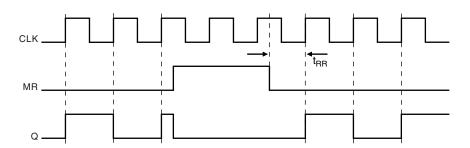


FIGURE 1. TIMING DIAGRAM

#### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V<sub>CC</sub> 4.6V

Inputs,  $V_I$  -0.5V to  $V_{CC}$  + 0.5 V

Outputs, I<sub>o</sub>

Continuous Current 50mA Surge Current 100mA

Package Thermal Impedance,  $\theta_{_{JA}} - 112.7^{\circ}\text{C/W}$  (0 lfpm)

Storage Temperature, T<sub>STG</sub> -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{CC} = 3.0V$  to 3.465V,  $V_{EE} = 0$ , Ta =  $-40^{\circ}$ C to  $85^{\circ}$ C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>cc</sub>	Positive Supply Voltage		3.0	3.3	3.465	V
I <sub>EE</sub>	Power Supply Current				104	mA

Table 4B. LVCMOS/LVTTL DC Characteristics,  $V_{CC} = 3.0V$  to 3.465V,  $V_{EE} = 0$ , Ta =  $-40^{\circ}$ C to  $85^{\circ}$ C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage			2		V <sub>cc</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage			-0.3		0.8	V
I <sub>IH</sub>	Input High Current	MR, F_SEL	$V_{CC} = V_{IN} = 3.465V$			150	μΑ
I <sub>IL</sub>	Input Low Current	MR, F_SEL	$V_{CC} = 3.465V, V_{IN} = 0V$	-5			μΑ

Table 4C. Differential DC Characteristics,  $V_{CC} = 3.0V$  to 3.465V,  $V_{FF} = 0$ , Ta =  $-40^{\circ}$ C to  $85^{\circ}$ C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	I lancit High Courset		$V_{CC} = V_{IN} = 3.465V$			150	μΑ
'IH	Input High Current	nCLK	$V_{CC} = V_{IN} = 3.465V$			5	μΑ
	I <sub>IL</sub> Input Low Current	CLK	$V_{CC} = 3.465V, V_{IN} = 0V$	-5			μΑ
I <sub>IL</sub>		nCLK	$V_{CC} = 3.465V, V_{IN} = 0V$	-150			μΑ
V <sub>PP</sub>	Peak-to-Peak Input Voltage			0.15		1.3	V
V <sub>CMR</sub>	Common Mode Input Voltage; NOTE 1, 2			V <sub>EE</sub> + 0.5		V <sub>CC</sub> - 0.85	V

NOTE 1: Common mode voltage is defined as  $V_{H}$ .

NOTE 2: For single ended applications, the maximum input voltage for CLK, nCLK is  $V_{cc}$  + 0.3V.

Table 4D. LVPECL DC Characteristics,  $V_{CC} = 3.0 V$  to 3.465 V,  $V_{EE} = 0$ , Ta =  $-40 ^{\circ} C$  to  $85 ^{\circ} C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>OH</sub>	Output High Voltage; NOTE 1		V <sub>cc</sub> - 1.4		V <sub>cc</sub> - 0.9	V
V <sub>OL</sub>	Output Low Voltage; NOTE 1		V <sub>cc</sub> - 2.0		V <sub>cc</sub> - 1.7	V
V <sub>SWING</sub>	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{cc}$  - 2V.

Table 5. AC Characteristics,  $V_{CC} = 3.0V$  to 3.465V,  $V_{EE} = 0$ , Ta =  $-40^{\circ}$ C to  $85^{\circ}$ C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>CLK</sub>	Clock Input Frequency	,				1	GHz
t <sub>PD</sub>	Propagation Delay; NOTE 1	CLK to Q (Dif)		1.7		2.1	ns
tsk(pp)	Part-to-Part Skew; NOTE 2, 3					300	ps
t <sub>RR</sub>	Reset Recovery Time					400	ps
t <sub>PW</sub>	Minimum Input Pulse Width	CLK		550			ps
$t_R/t_F$	Output Rise/Fall Time		20% to 80%	300		600	ps
odc	Output Duty Cycle			48		52	%

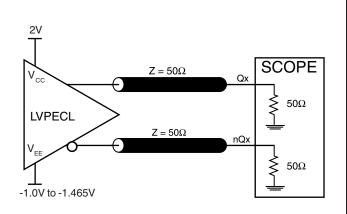
NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

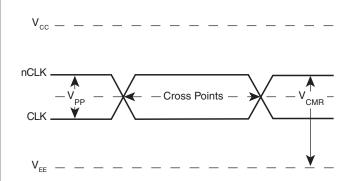
NOTE 2: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.



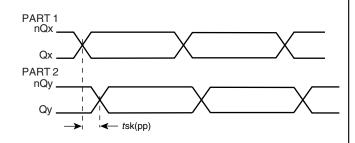
## PARAMETER MEASUREMENT INFORMATION

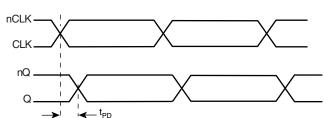




#### 3.3V OUTPUT LOAD AC TEST CIRCUIT

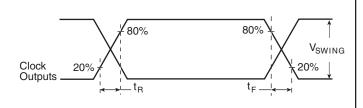
#### DIFFERENTIAL INPUT LEVEL

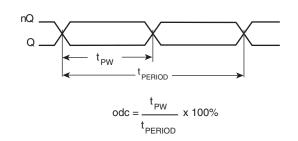




#### PART-TO-PART SKEW

#### PROPAGATION DELAY





#### **OUTPUT RISE/FALL TIME**

#### OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

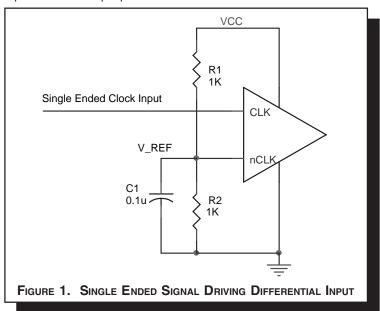


### APPLICATION INFORMATION

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{CC}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\rm CC}$  = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.



#### TERMINATION FOR 3.3V LVPECL OUTPUT

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

 $50\Omega$  transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figures 2A and 2B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

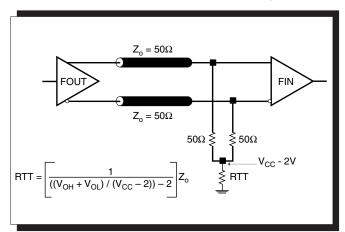


FIGURE 2A. LVPECL OUTPUT TERMINATION

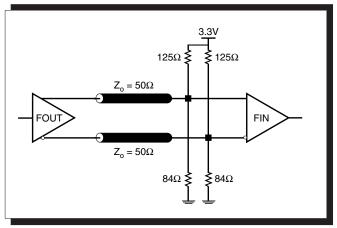


FIGURE 2B. LVPECL OUTPUT TERMINATION



#### DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK/nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both  $V_{\text{SWING}}$  and  $V_{\text{OH}}$  must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 3A to 3E show interface examples for the HiPerClockS CLK/nCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 3A*, the input termination applies for ICS HiPerClockS LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

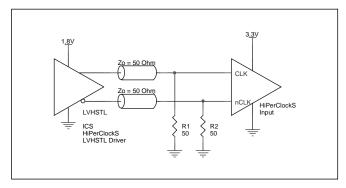


FIGURE 3A. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY ICS HIPERCLOCKS LVHSTL DRIVER

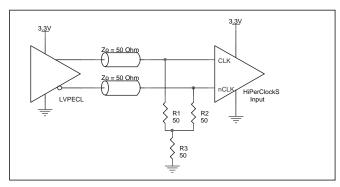


FIGURE 3B. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

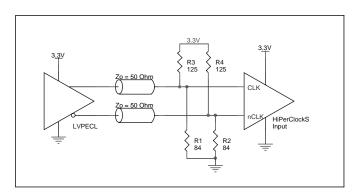


FIGURE 3C. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

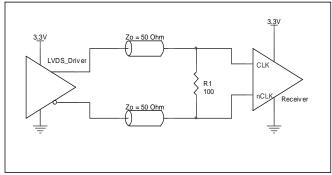


FIGURE 3D. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

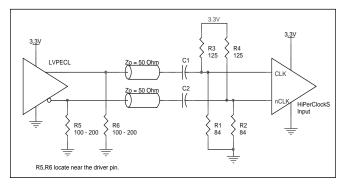


FIGURE 3E. HIPERCLOCKS CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER WITH AC COUPLE

### POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS87354I. Equations and example calculations are also provided.

#### 1. Power Dissipation.

The total power dissipation for the ICS87354I is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.465V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> = V<sub>CC\_MAX</sub> \* I<sub>EE\_MAX</sub> = 3.465V \* 104mA = 360mW
- Power (outputs)<sub>MAX</sub> = 3.465mW/Loaded Output pair

Total Power MAX (3.465V, with all outputs switching) = 360mW + 30mW = 390mW

#### 2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS $^{\text{TM}}$  devices is 125 $^{\circ}$ C.

The equation for Tj is as follows: Tj =  $\theta_{JA}$  \* Pd\_total + T<sub>A</sub>

Tj = Junction Temperature

 $\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

Pd\_total = Total Device Power Dissipation (example calculation is in section 1 above)

 $T_A = Ambient Temperature$ 

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{\rm JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 103.3°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance  $\theta_{\rm JA}$  for 8-pin SOIC, Forced Convection

# 0200500Single-Layer PCB, JEDEC Standard Test Boards153.3°C/W128.5°C/W115.5°C/WMulti-Layer PCB, JEDEC Standard Test Boards112.7°C/W103.3°C/W97.1°C/W

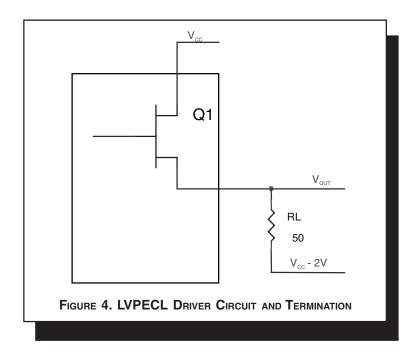
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

θ<sub>1</sub>, by Velocity (Linear Feet per Minute)

#### 3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in Figure 4.



To calculate worst case power dissipation into the load, use the following equations which assume a  $50\Omega$  load, and a termination voltage of  $V_{CC}$  - 2V.

• For logic high, 
$$V_{OUT} = V_{OH\_MAX} = V_{CC\_MAX} - 0.9V$$

$$(V_{CC\_MAX} - V_{OH\_MAX}) = 0.9V$$

• For logic low, 
$$V_{OUT} = V_{OL\_MAX} = V_{CC\_MAX} - 1.7V$$

$$(V_{CC\_MAX} - V_{OL\_MAX}) = 1.7V$$

Pd\_H is power dissipation when the output drives high. Pd\_L is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_{L}] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_{L}] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd\_L = [(V_{\text{OL\_MAX}} - (V_{\text{CC\_MAX}} - 2V))/R_{\text{L}}] * (V_{\text{CC\_MAX}} - V_{\text{OL\_MAX}}) = [(2V - (V_{\text{CC\_MAX}} - V_{\text{OL\_MAX}}))/R_{\text{L}}] * (V_{\text{CC\_MAX}} - V_{\text{OL\_MAX}}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd\_H + Pd\_L = 30mW



## **RELIABILITY INFORMATION**

## Table 6. $\theta_{\text{JA}} \text{vs. Air Flow Table for 8 Lead SOIC}$

### $\theta_{JA}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for ICS87354I is: 1745



#### PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

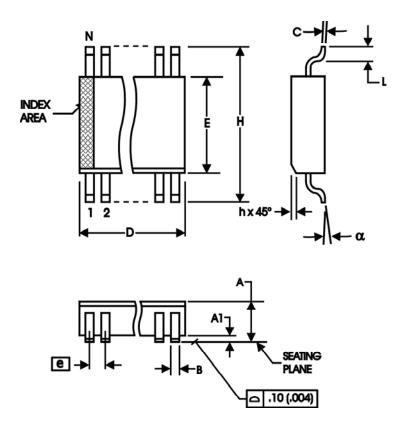


TABLE 7. PACKAGE DIMENSIONS

SYMBOL	Millin	neters
STWBOL	MINIMUN	MAXIMUM
N		8
А	1.35	1.75
A1	0.10	0.25
В	0.33	0.51
С	0.19	0.25
D	4.80	5.00
E	3.80	4.00
е	1.27 [	BASIC
Н	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012

## **ICS87354I**

# ÷4/÷5 DIFFERENTIAL-TO-3.3V LVPECL CLOCK GENERATOR

#### TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS87354AMI	87354AMI	8 lead SOIC	tube	-40°C to 85°C
ICS87354AMIT	87354AMI	8 lead SOIC	2500 tape & reel	-40°C to 85°C
ICS87354AMILF	87354AIL	8 lead "Lead-Free" SOIC	tube	-40°C to 85°C
ICS87354AMILFT	87354AIL	8 lead "Lead-Free" SOIC	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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